

8.89mmx8.89mm LED LIGHT BAR

Part Number: KB2755YW Yellow

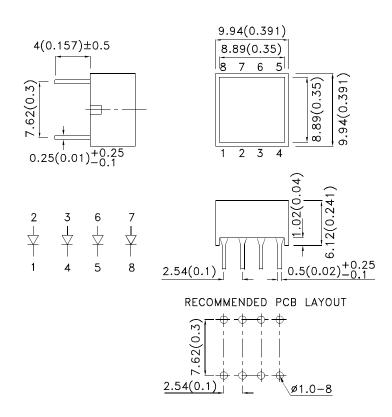
Features

- Uniform light emitting area.
- Easily mounted on P.C. boards.
- Flush mountable.
- Excellent on/off contrast.
- Can be used with panels and legend mounts.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram





1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.

2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAD1452 REV NO: V.8A DATE: OCT/27/2012

APPROVED: WYNEC CHECKED: Joe Lee DRAWN: C.H.Han



E: OCT/27/2012 PAGE: 1 OF 6

WN: C.H.Han ERP: 1334000168

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [1] @ 20mA	
		-	Min.	Тур.
KB2755YW	Yellow (GaAsP/GaP)	White Diffused	20	51
KB27331W	Tellow (GaASF/GaF)	Ville Dilused		*17

Notes:

- Luminous intensity/ luminous Flux: +/-15%.
 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA
lr	Reverse Current	Yellow		10	uA	VR=5V

Notes:

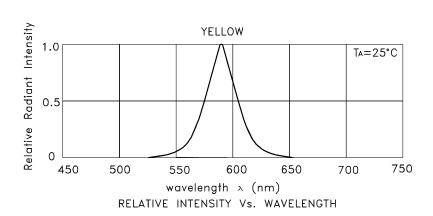
- 1.Wavelength: +/-1nm.
 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

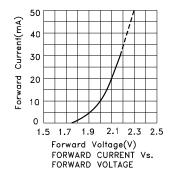
Parameter	Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating / Storage Temperature -40°C To +85°C		
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

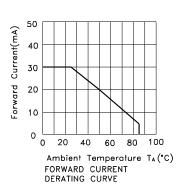
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.

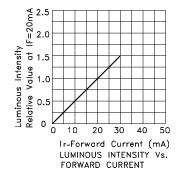
SPEC NO: DSAD1452 **REV NO: V.8A** DATE: OCT/27/2012 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED:** Joe Lee DRAWN: C.H.Han ERP: 1334000168

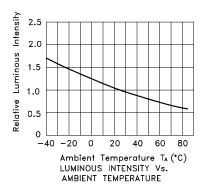


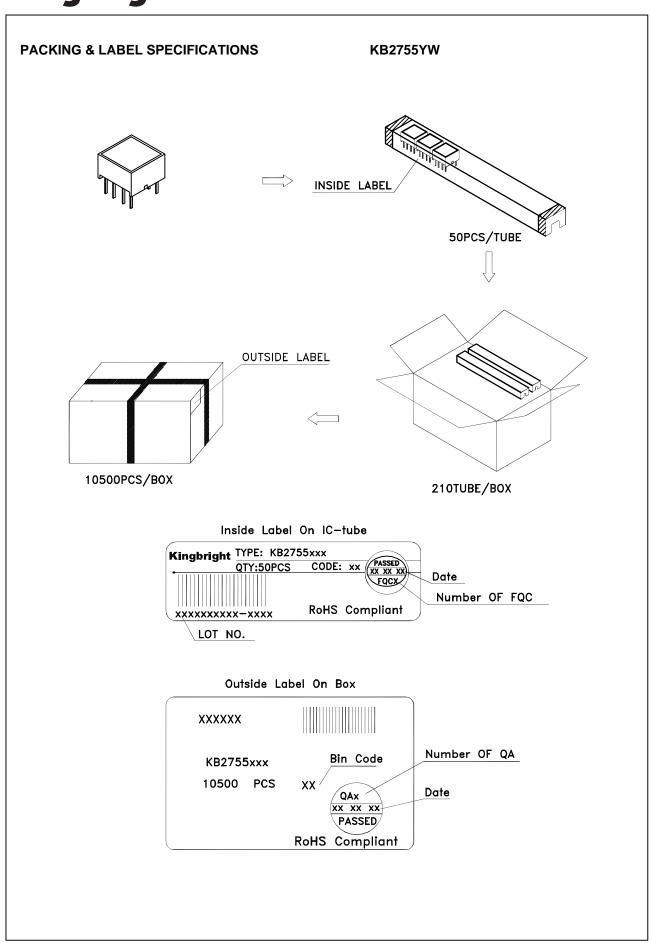
Yellow KB2755YW









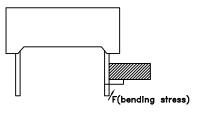


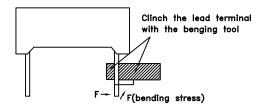
SPEC NO: DSAD1452 APPROVED: WYNEC REV NO: V.8A CHECKED: Joe Lee DATE: OCT/27/2012 DRAWN: C.H.Han PAGE: 4 OF 6 ERP: 1334000168

THROUGH HOLE DISPLAY MOUNTING METHOD

Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



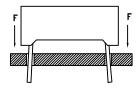


Not Recommended

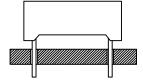
Recommended

Installation

- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.

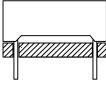


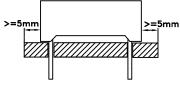
Not Recommended



Recommended

3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



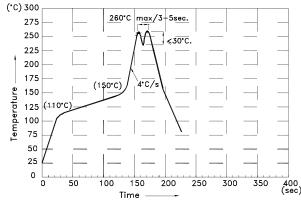


Not Recommended Recommended

SPEC NO: DSAD1452 APPROVED: WYNEC REV NO: V.8A CHECKED: Joe Lee DATE: OCT/27/2012 DRAWN: C.H.Han PAGE: 5 OF 6 ERP: 1334000168

DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering , the PCB top-surface temperature should be kept below 105°C
- 5.No more than once.

Soldering General Notes:

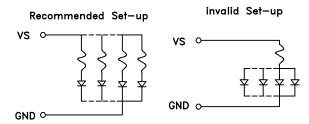
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

 SPEC NO: DSAD1452
 REV NO: V.8A
 DATE: OCT/27/2012
 PAGE: 6 OF 6

 APPROVED: WYNEC
 CHECKED: Joe Lee
 DRAWN: C.H.Han
 ERP: 1334000168